## 2SA1791

## Silicon PNP epitaxial planar type

For low-frequency amplification Complementary to 2SC4656

#### ■ Features

- High forward current transfer ratio f<sub>T</sub>
- Small collector output capacitance Cob
- SS-Mini type package allowing downsizing of the equipment and automatic insertion through the tape packing

### ■ Absolute Maximum Ratings $T_a = 25$ °C

| Parameter                             | Symbol           | Rating      | Unit |  |
|---------------------------------------|------------------|-------------|------|--|
| Collector-base voltage (Emitter open) | V <sub>CBO</sub> | -50         | V    |  |
| Collector-emitter voltage (Base open) | V <sub>CEO</sub> | -50         | V    |  |
| Emitter-base voltage (Collector open) | $V_{EBO}$        | -5          | V    |  |
| Collector current                     | $I_{\rm C}$      | -50         | mA   |  |
| Collector power dissipation           | P <sub>C</sub>   | 125         | mW   |  |
| Junction temperature                  | Tj               | 125         | °C   |  |
| Storage temperature                   | T <sub>stg</sub> | -55 to +125 | °C   |  |



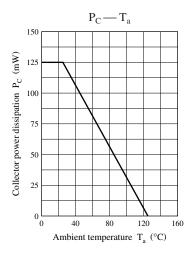
### ■ Electrical Characteristics T<sub>a</sub> = 25°C

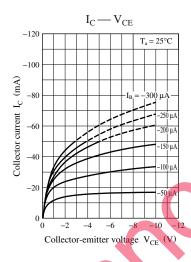
| Parameter                                    | Symbol               | Conditions  | Min | Тур   | Max   | Unit |
|--|----------------------|---|-----|-------|-------|------|
| Collector-base voltage (Emitter open)        | $V_{CBO}$            | $I_{\rm C} = -10  \mu \text{A}$ $I_{\rm E} = 0$                   | -50 |       |       | V    |
| Collector-emitter voltage (Base open)        | V <sub>CEO</sub>     | $I_C = -1$ mA, $I_B = 0$  | -50 |       |       | V    |
| Emitter-base voltage (Collector open)        | V <sub>EBO</sub>     | $I_{\rm H} = 10  \mu A, I_{\rm O} = 0$                            | -5  |       |       | V    |
| Collector-base cutoff current (Emitter open) | $I_{CBO}$            | $V_{CB} = -10 \text{ V}, I_E = 0$                                 |     |       | - 0.1 | μΑ   |
| Collector-emitter cutoff current (Base open) | I <sub>CEQ</sub>     | $V_{CE} = 10 \text{ V}, I_B = 0$                                  |     |       | -100  | μΑ   |
| Forward current transfer ratio *             | h <sub>EE</sub>      | $V_{CE} = -10 \text{ V}, I_{C} = -2 \text{ mA}$                   | 200 |       | 500   | _    |
| Collector-emitter saturation voltage         | V <sub>CE(sat)</sub> | $I_{\rm C} = -10 \text{ mA}, I_{\rm B} = -1 \text{ mA}$           |     | - 0.1 | - 0.3 | V    |
| Transition frequency                         | f                    | $V_{CB} = -10 \text{ V}, I_E = 2 \text{ mA}, f = 200 \text{ MHz}$ |     | 250   |       | MHz  |
| Collector output capacitance                 | Cob                  | $V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$              |     | 1.5   |       | pF   |
| (Common base, input open circuited)          |                      |   |     |       |       |      |

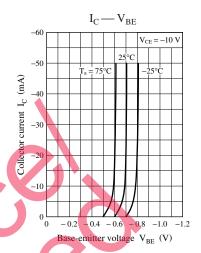
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

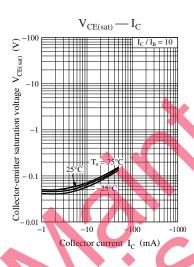
#### 2. \*: Rank classification

| Rank     | Q          | R          |  |  |
|----------|------------|------------|--|--|
| $h_{FE}$ | 200 to 400 | 250 to 500 |  |  |

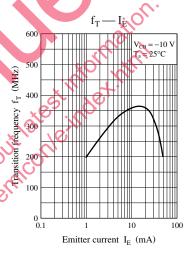


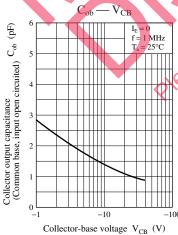












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